EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	436	438/111.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 14:03
L2	29	(US-20050012189-$ or US-20010019181-$ or US-20020006718-$ or US-20020149092-$ or US-20020180035-$ or US-20020187590-$ or US-20030034569-$ or US-20030071348-$ or US-20030092221-$ or US-20030203539-$ or US-20040195701-$ or US-20050003585-$ or US-20050012203-$ or US-20030176020-$ or US-20040212080-$).did. or (US-6444498-$ or US-5258648-$ or US-5311060-$ or US-6228683-$ or US-6323066-$ or US-6432749-$ or US-6559537-$ or US-6709895-$ or US-6734552-$ or US-6853070-$ or US-6861750-$ or US-6873039-$ or US-6933176-$ or US-6607942-$).did.	US-PGPUB; USPAT	OR	ON	2006/07/12 14:04
L3	592	438/112.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 15:06
L5	865	438/122.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 15:31
L6	274	438/122.ccls. and (strip or array or line) near3 (substrate or package or pcb or pwb or circuit near board or wiring near board or leadframe or lead adj frame)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 15:32

L8	30	438/122.ccls. and (underfill$4 or under-fill$4) and (tim or thermal near interface or conductive near adhesive or thermal near adhesive) and (heatsink or heatsinking or (heat or heating or thermal$2) near (sink or sinking or slug or spread$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 17:00
L9	1199	257/E23.101.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 15:51
L10	252	257/E23.129.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 16:05
L13	157	257/E23.133.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 16:19
L14	1637	257/E21.502.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 16:19
L16	644	257/E23.101,E21.502.ccls. and (strip or array or line) near3 (substrate or package or pcb or pwb or circuit near board or wiring near board or leadframe or lead adj frame)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 16:41
L18	85	257/E23.101,E21.502.ccls. and (underfill$4 or under-fill$4) and (tim or thermal near interface or conductive near adhesive or thermal near adhesive) and (heatsink or heatsinking or (heat or heating or thermal$2) near (sink or sinking or slug or spread$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 17:01

S42	30	("20010015492" | "20020005578" | "20020006718" | "20020180035" | "20020185734" | "20030034569" | "5172213" | "5311060" | "5339216" | "5444025" | "5493153" | "5610442" | "5639694" | "5650663" | "5679978" | "5705851" | "5736785" | "5773362" | "5877552" | "5977626" | "5986885" | "6037658" | "6236568" | "6251706" | "6323066" | "6414385" | "6462405" | "6525421" | "6631078" | "6656770"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/10 10:04
S43	109	("20020079570" | "3908075" | "3942245" | "4501960" | "4674175" | "4701781" | "4975765" | "5023202" | "5041395" | "5122860" | "5157475" | "5172213" | "5175612" | "5285105" | "5334857" | "5366933" | "5420460" | "5474957" | "5482736" | "5482898" | "5485037" | "5556807" | "5596231" | "5596485" | "5620928" | "5650593" | "5672548" | "5672909" | "5679978" | "5693572" | "5708567" | "5729432" | "5736785" | "5789813" | "5796163" | "5807768" | "5854511" | "5867368" | "5874321" | "5886397" | "5894108" | "5900676" | "5939784" | "5940271" | "5949655" | "5950074" | "5962810" | "5981314" | "5982621" | "5986336" | "5986340" | "6011304" | "6028354" | "6034429" | "6049125" | "6069023" | "6081028" | "6081029" | "6091603" | "6092281" | "6097101" | "6104086" | "6111324" | "6117193" | "6117705" | "6127724" | "6143588" | "6150193" | "6162849" | "6163458" | "6165612" | "6191360" | "6196002" | "6198163" | "6206997" | "6208519" | "6212070" | "6214644" | "6219238" | "6222263" | "6228676" | "6229200" | "6229702" | "6236568" | "6242281" | "6246566" | "6258629" | "6265771" | "6266197" | "6274927" | "6281241" | "6281568" | "6285075" | "6291884" | "6294100" | "6294830" | "6326678" | "6395578" | "6396143" | "6429048" | "6429508" | "6433360" | "6444498" | "6452255" | "6458626" | "6498099" | "6507102" | "6552417" | "6556740").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/10 10:46

EAST Search History

S44	810	(strip or array or line) near (substrate or pcb or leadframe or lead adj frame or package) near8 (chip or die or ic or integrated near circuit or semiconductor near device) and ((heat or heating or thermal$2) near (sink or slug or spreader or spreading or dissipation or dissipating or sinking or extract$3 or removal or removing) or heatsink or heatsinking) and (mold or molding or overmolding or encapsulat$4) and (bga or ball near grid or solder near ball or solder near bump or flip adj chip)	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/10 10:51
S45	614	(strip or array or line) near (substrate or pcb or leadframe or lead adj frame or package) near8 (chip or die or ic or integrated near circuit or semiconductor near device) and ((heat or heating or thermal$2) near (sink or slug or spreader or spreading or sinking) or heatsink or heatsinking) and (mold or molding or overmolding or encapsulat$4) and (bga or ball near grid or solder near ball or solder near bump or flip adj chip)	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/10 10:52
S46	180	(strip or line) near (substrate or pcb or leadframe or lead adj frame or package) near8 (chip or die or ic or integrated near circuit or semiconductor near device) and ((heat or heating or thermal$2) near (sink or slug or spreader or spreading or sinking) or heatsink or heatsinking) and (mold or molding or overmolding or encapsulat$4) and (bga or ball near grid or solder near ball or solder near bump or flip adj chip)	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/10 10:53
S47	185	(strip or line) near (substrate or pcb or leadframe or lead adj frame or package) near8 (chip or die or ic or integrated near circuit or semiconductor near device) and ((heat or heating or thermal$2) near (sink or slug or spreader or spreading or sinking) or heatsink or heatsinking) and (mold or molding or overmolding or encapsulat$4) and (bga or ball near grid or solder near ball or solder near bump or flip adj chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/10 10:53

S48	28	(US-20050012203-$ or US-20030203539-$ or US-20030071348-$ or US-20020187590-$ or US-20040195701-$ or US-20030092221-$ or US-20050003585-$ or US-20020149092-$ or US-20030034569-$ or US-20020006718-$ or US-20020180035-$ or US-20010019181-$ or US-20050012189-$ or US-20030176020-$).did. or (US-6861750-$ or US-6873039-$ or US-5311060-$ or US-5258648-$ or US-6228683-$ or US-6933176-$ or US-6709895-$ or US-6734552-$ or US-6432749-$ or US-6323066-$ or US-6853070-$ or US-6559537-$ or US-6444498-$ or US-6607942-$).did.	US-PGPUB; USPAT	OR	ON	2006/07/10 12:08
S49	338	(chip or die or integrated adj circuit or ic) and (substrate or leadframe or frame or package or packaging or housing) near2 (strip or tape) and (heatsink or (heat or thermal$2) near2 (sink or spread$3)) and (encapsulat$4 or encapsulant or molding or mold) near6 (open or expos$4 or uncover$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/10 13:20
S50	135	(substrate or leadframe or frame or package or packaging or housing) near2 (strip or tape) and (heatsink or (heat or thermal$2) near2 (sink or spread$3)) near6 (chip or die or ic or integrated adj circuit) near20 ((thermal$2 or heat$2) near2 (interface or adhesive) or tim)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/10 13:39
S51	501	(substrate or package or packaging or circuit adj board or wiring near board or pcb or pwb or interposer) near3 (strip) and (chip or die or integrated adj circuit or ic) near5 ((heat or thermal$3) near (sink or spreader or spreading or dissipat$4 or conduct$4) or heatsink) and (encapsul$4 or molding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/10 13:49

S52	173	(substrate or package or packaging or circuit adj board or wiring near board or pcb or pwb or interposer) near3 (strip or panel) and (chip or die or integrated adj circuit or ic) near5 ((heat or thermal$3) near (sink or spreader or spreading or dissipat$4 or conduct$4) or heatsink) same (encapsul$4 or molding) and (ball near grid or solder near ball or solder near bump or bga)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/10 14:31
S53	460	257/706.ccls. and (strip or array or line) near3 (substrate or package or pcb or pwb or circuit near board or wiring near board or leadframe or lead adj frame)	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/12 16:19
S54	0	257/706.ccls. and (open near encapsula$5)	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/10 15:20
S55	85	257/706.ccls. and (underfill$4 or under-fill$4) and (tim or thermal near interface or conductive near adhesive or thermal near adhesive) and (heatsink or heatsinking or (heat or heating or thermal$2) near (sink or sinking or slug or spread$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/10 16:05
S56	1011	257/707.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/10 15:31
S57	338	257/707.ccls. and (strip or array or line) near3 (substrate or package or pcb or pwb or circuit near board or wiring near board or leadframe or lead adj frame)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 15:32
S58	40	257/707.ccls. and (underfill$4 or under-fill$4) and (tim or thermal near interface or conductive near adhesive or thermal near adhesive) and (heatsink or heatsinking or (heat or heating or thermal$2) near (sink or sinking or slug or spread$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 15:47
S59	438	257/712.ccls. and (strip or array or line) near3 (substrate or package or pcb or pwb or circuit near board or wiring near board or leadframe or lead adj frame)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/10 17:08

S60	14	"6225695".pn. "6051888".pn. "20020163075" "20020109241" "5864178".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/10 17:08

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	strip near open near encapsulation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 09:11
L3	379	((heat or thermal$2) near2 (spread$4 or sink or sinking or slug) or heatsink or heatsinking) and (underfill$3 or under adj fill$3) and (singulat$4 or dicing or diced or scribing or scribed or separating or separated or sawed or cleaving or cleaved) near4 (dice or package or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 12:43
L4	13	("4687879" | "4882298" | "5550408" | "5667884" | "5672548" | "5710071" | "5737191" | "5835355" | "5969426" | "5998241" | "6069023" | "6160714" | "6347037").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/12 11:22
L5	0	("6720650").URPN.	USPAT	OR	ON	2006/07/12 11:26
L6	0	("6660565").URPN.	USPAT	OR	ON	2006/07/12 11:27
L7	12	("20020070445" | "5385869" | "5726079" | "5817545" | "5883430" | "5896271" | "5898224" | "5909056" | "5990418" | "6117797" | "6309908" | "6468832").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/12 12:41
L8	15	open adj encapsulation	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/12 12:42
L9	45	((heat or thermal$2) near2 (spread$4 or sink or sinking or slug) or heatsink or heatsinking) and (underfill$3 or under adj fill$3) and (tim or thermal near interface or thermal$2 near adhesive) and (singulat$4 or dicing or diced or scribing or scribed or separating or separated or sawed or cleaving or cleaved) near4 (dice or package or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 13:50
L10	2	"6660565".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 13:50
L11	12	("20020070445" | "5385869" | "5726079" | "5817545" | "5883430" | "5896271" | "5898224" | "5909056" | "5990418" | "6117797" | "6309908" | "6468832").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/12 13:50

EAST Search History

| L12 | 21 | (US-20010023983-$ or US-20040040740-$ or US-20030171456-$ or US-20020035201-$ or US-20030170450-$ or US-20030080437-$ or US-20020131253-$ or US-20020062970-$ or US-20030075805-$ or US-20040084688-$ or US-20020008316-$).did. or (US-6409070-$ or US-5493259-$ or US-6011683-$ or US-6727119-$ or US-6555414-$ or US-6440777-$ or US-6399178-$ or US-6018192-$ or US-5529957-$ or US-6459561-$).did. | US-PGPUB; USPAT | OR | ON | 2006/07/12 14:02 |